Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	324	moisture near wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:14
S1	750	trivalent adj titanium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 13:30
S2	1441	divalent adj iron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 13:31
S3	1159912	рН	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 13:31
S4	243020	fluorine	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 13:31
S6	3	S1 and S2 and S3 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 10:55
S7	324	moisture near wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 10:55
S8	7548603	surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 10:56
S9	31	S7 near S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/06/12 10:56

S10	1684598	sence or sensor or infra	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 11:00
S11	4	S9 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 10:56
S12	2286444	sense or sensor or infra	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 11:00
S14	2	"20040043153"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/12 13:17
S15	1	"20040043153"	DERWENT	OR	ON	2006/06/12 13:17
S16	1	"20040043153".pfpn.	DERWENT	OR	ON	2006/06/12 13:18
S17	1	"20040043153"	DERWENT	OR	ON	2006/06/12 14:16
S18	1	2004-293454.NRAN.	DERWENT	OR	ON	2006/06/12 14:16
S19	1	2004-293454.NRAN.	DERWENT	OR	ON	2006/06/12 14:16

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	324	moisture near wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:14
L3	7558658	surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:14
L4	31	L2 near L3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:16
L5	2291192	sense or sensor or infra	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:14
L6	4	L4 and L5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:14
L7	29384	(circuit adj board) with roughen or roughening	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:16
L8	7261	7 and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:17
L9	771297	8 and copper alloy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:16
L10	771297	I8 and copper alloy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:16

L11	771297	L8 and copper alloy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:16
L12	4152	8 and alloy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:17
L13	1173	12 and acidic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:17
L14	199	13 and oxidant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:17
L15	. 174	14 and peroxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:18
L16	6176695	15 no halogen	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:18
L17	6176695	L15 no halogen	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:18
L18	13	L15 not halogen	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/21 13:18